

# BLC9G15LS-400AVT

Power LDMOS transistor

Rev. 3 — 24 November 2017

AMPLEON

Product data sheet

## 1. Product profile

### 1.1 General description

400 W LDMOS packaged asymmetric Doherty power transistor for base station applications at frequencies from 1452 MHz to 1511 MHz.

**Table 1. Typical performance**

Typical RF performance at  $T_{case} = 25\text{ °C}$  in an asymmetrical Doherty production test circuit.  
 $V_{DS} = 32\text{ V}$ ;  $I_{DQ} = 810\text{ mA}$  (main);  $V_{GS(amp)peak} = 0.5\text{ V}$ , unless otherwise specified.

Test signal	f	$V_{DS}$	$P_{L(AV)}$	$G_p$	$\eta_D$	ACPR
	(MHz)	(V)	(W)	(dB)	(%)	(dBc)
1-carrier W-CDMA	1452 to 1511	32	93	16.5	48	-35 [1]

[1] Test signal: 1-carrier W-CDMA; 3GPP test model 1; 64 DPCH; PAR = 9.6 dB at 0.01 % probability on CCDF.

### 1.2 Features and benefits

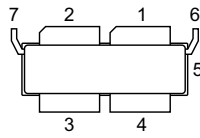
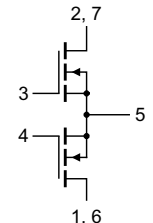
- Excellent ruggedness
- High efficiency
- Low thermal resistance providing excellent thermal stability
- Lower output capacitance for improved performance in Doherty applications
- Designed for low memory effects providing excellent digital pre-distortion capability
- Internally matched for ease of use
- Integrated ESD protection
- Compliant to Directive 2002/95/EC, regarding Restriction of Hazardous Substances (RoHS)

### 1.3 Applications

- RF power amplifiers for base stations and multi carrier applications in the 1452 MHz to 1511 MHz frequency range

## 2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	drain2 (peak)		
2	drain1 (main)		
3	gate1 (main)		
4	gate2 (peak)		
5	source <sup>[1]</sup>		
6	video decoupling (peak)		
7	video decoupling (main)		

[1] Connected to flange.

## 3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BLC9G15LS-400AVT	-	air cavity plastic earless flanged package; 6 leads	SOT1258-1

## 4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DS}$	drain-source voltage		-	65	V
$V_{GS(amp)main}$	main amplifier gate-source voltage		-6	+13	V
$V_{GS(amp)peak}$	peak amplifier gate-source voltage		-6	+13	V
$T_{stg}$	storage temperature		-65	+150	°C
$T_j$	junction temperature		<sup>[1]</sup> -	225	°C
$T_{case}$	case temperature	operating	<sup>[1]</sup> -40	+125	°C

[1] Continuous use at maximum temperature will affect the reliability, for details refer to the online MTF calculator.

## 5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-c)}$	thermal resistance from junction to case	$V_{DS} = 32 \text{ V}$ ; $I_{DQ} = 980 \text{ mA}$ (main); $V_{GS(amp)peak} = 0,4 \text{ V}$ ; $T_{case} = 80 \text{ °C}$		
		$P_L = 93 \text{ W}$	0.31	k/W
		$P_L = 117 \text{ W}$	0.29	k/W

## 6. Characteristics

**Table 6. DC characteristics**

$T_j = 25\text{ °C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Main device</b>						
$V_{(BR)DSS}$	drain-source breakdown voltage	$V_{GS} = 0\text{ V}; I_D = 1.62\text{ mA}$	65	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$V_{DS} = 10\text{ V}; I_D = 162\text{ mA}$	1.5	2.0	2.5	V
$V_{GSq}$	gate-source quiescent voltage	$V_{DS} = 32\text{ V}; I_D = 810\text{ mA}$	1.65	2.15	2.65	V
$I_{DSS}$	drain leakage current	$V_{GS} = 0\text{ V}; V_{DS} = 32\text{ V}$	-	-	2.8	$\mu\text{A}$
$I_{DSX}$	drain cut-off current	$V_{GS} = V_{GS(th)} + 3.75\text{ V}$	-	32	-	A
$I_{GSS}$	gate leakage current	$V_{GS} = 11\text{ V}; V_{DS} = 0\text{ V}$	-	-	280	nA
$g_{fs}$	forward transconductance	$V_{DS} = 10\text{ V}; I_D = 8.1\text{ A}$	-	11.5	-	S
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 3.75\text{ V}; I_D = 5.67\text{ A}$	-	85	149	$\text{m}\Omega$
<b>Peak device</b>						
$V_{(BR)DSS}$	drain-source breakdown voltage	$V_{GS} = 0\text{ V}; I_D = 3.0\text{ mA}$	65	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$V_{DS} = 10\text{ V}; I_D = 300\text{ mA}$	1.5	2.0	2.5	V
$V_{GSq}$	gate-source quiescent voltage	$V_{DS} = 32\text{ V}; I_D = 1500\text{ mA}$	1.65	2.15	2.65	V
$I_{DSS}$	drain leakage current	$V_{GS} = 0\text{ V}; V_{DS} = 32\text{ V}$	-	-	2.8	$\mu\text{A}$
$I_{DSX}$	drain cut-off current	$V_{GS} = V_{GS(th)} + 3.75\text{ V}$	-	52	-	A
$I_{GSS}$	gate leakage current	$V_{GS} = 11\text{ V}; V_{DS} = 0\text{ V}$	-	-	280	nA
$g_{fs}$	forward transconductance	$V_{DS} = 10\text{ V}; I_D = 15\text{ A}$	-	20.5	-	S
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 3.75\text{ V}; I_D = 10.5\text{ A}$	-	46	85	$\text{m}\Omega$

**Table 7. RF characteristics**

Test signal: 1-carrier W-CDMA; PAR = 9.6 dB at 0.01 % probability on the CCDF;  
3GPP test model 1; 1 to 64 DPCH;  $f_1 = 1455\text{ MHz}$ ;  $f_2 = 1508.5\text{ MHz}$ ; RF performance at  $V_{DS} = 32\text{ V}$ ;  
 $I_{Dq} = 810\text{ mA}$  (main);  $V_{GS(amp)peak} = 0.5\text{ V}$ ;  $T_{case} = 25\text{ °C}$ ; unless otherwise specified; in an  
asymmetrical Doherty production test circuit at frequencies from 1452 MHz to 1511 MHz.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$G_p$	power gain	$P_{L(AV)} = 93\text{ W}$	15	16.2	-	dB
$RL_{in}$	input return loss	$P_{L(AV)} = 93\text{ W}$	-	-15	-10	dB
$\eta_D$	drain efficiency	$P_{L(AV)} = 93\text{ W}$	46.5	51	-	%
ACPR	adjacent channel power ratio	$P_{L(AV)} = 93\text{ W}$	-	-34	-29	dBc

**Table 8. RF characteristics**

Test signal: 1-carrier W-CDMA; PAR = 9.6 dB at 0.01 % probability on the CCDF;  
3GPP test model 1; 1 to 64 DPCH;  $f = 1508.5\text{ MHz}$ ; RF performance at  $V_{DS} = 32\text{ V}$ ;  
 $I_{Dq} = 810\text{ mA}$  (main);  $V_{GS(amp)peak} = 0.5\text{ V}$ ;  $T_{case} = 25\text{ °C}$ ; unless otherwise specified; in an  
asymmetrical Doherty production test circuit at a frequency of 1511 MHz.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$PAR_O$	output peak-to-average ratio	$P_{L(AV)} = 110\text{ W}$	6.3	6.9	-	dB
$P_{L(M)}$	peak output power	$P_{L(AV)} = 110\text{ W}$	460	540	-	W

## 7. Test information

### 7.1 Ruggedness in Doherty operation

The BLC9G15LS-400AVT is capable of withstanding a load mismatch corresponding to VSWR = 10 : 1 through all phases under the following conditions:  $V_{DS} = 32$  V;  $I_{DQ} = 810$  mA;  $V_{GS(amp)peak} = 0.5$  V;  $f = 1454.5$  MHz;  $P_L = 126$  W (5 dB OBO); 1-carrier W-CDMA; 100 % clipping.

### 7.2 Impedance information

**Table 9. Typical impedance of main device**

Measured load-pull data of main device;  $I_{DQ} = 810$  mA (main);  $V_{DS} = 30$  V; pulsed CW ( $t_p = 100$   $\mu$ s;  $\delta = 10$  %).

f	Z <sub>S</sub> [1]	Z <sub>L</sub> [1]	P <sub>L</sub> [2]	$\eta_D$ [2]	G <sub>p</sub> [2]
(MHz)	( $\Omega$ )	( $\Omega$ )	(W)	(%)	(dB)
<b>Maximum power load</b>					
1440	1.0 – j4.8	0.9 – j3.4	245	53.5	18.0
1480	1.4 – j5.3	0.9 – j3.7	245	55.6	18.3
1510	1.5 – j5.7	1.0 – j4.0	245	57.1	18.7
<b>Maximum drain efficiency load</b>					
1440	1.0 – j4.8	2.5 – j3.1	170	71.8	21.4
1480	1.4 – j5.3	2.5 – j2.9	153	72.3	21.8
1510	1.5 – j5.7	2.5 – j3.0	153	71.2	21.9

[1] Z<sub>S</sub> and Z<sub>L</sub> defined in [Figure 1](#).

[2] At 3 dB gain compression.

**Table 10. Typical impedance of peak device**

Measured load-pull data of peak device;  $I_{DQ} = 1800$  mA (peak);  $V_{DS} = 30$  V; pulsed CW ( $t_p = 100$   $\mu$ s;  $\delta = 10$  %).

f	Z <sub>S</sub> [1]	Z <sub>L</sub> [1]	P <sub>L</sub> [2]	$\eta_D$ [2]	G <sub>p</sub> [2]
(MHz)	( $\Omega$ )	( $\Omega$ )	(W)	(%)	(dB)
<b>Maximum power load</b>					
1440	2.0 – j7.6	1.5 – j3.4	390	54.3	19.4
1480	3.0 – j8.0	1.6 – j3.4	400	57.0	19.7
1510	2.8 – j9.2	1.8 – j3.6	390	55.4	19.8
<b>Maximum drain efficiency load</b>					
1440	2.0 – j7.6	3.1 – j1.4	255	67.3	22.4
1480	3.0 – j8.0	2.5 – j1.7	271	68.3	22.3
1510	2.8 – j9.2	2.2 – j1.9	283	67.2	22.4

[1] Z<sub>S</sub> and Z<sub>L</sub> defined in [Figure 1](#).

[2] At 3 dB gain compression.

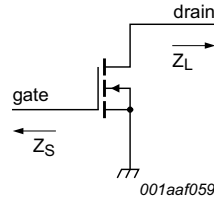


Fig 1. Definition of transistor impedance

### 7.3 Recommended impedances for Doherty design

**Table 11. Typical impedance of main at 1 : 1 load**

Measured load-pull data of main device;  $I_{Dq} = 810$  mA (main);  $V_{DS} = 30$  V; pulsed CW ( $t_p = 100$   $\mu$ s;  $\delta = 10$  %).

f	$Z_S$ [1]	$Z_L$ [1]	$P_{L(3dB)}$ [2]	$\eta_D$ [2]	$G_p$ [2]
(MHz)	( $\Omega$ )	( $\Omega$ )	(W)	(%)	(dB)
1440	$1.0 - j4.8$	$1.50 - j4.2$	220	45	19.5
1480	$1.4 - j5.3$	$1.40 - j3.7$	230	46	19.6
1510	$1.5 - j5.7$	$1.38 - j3.5$	220	47	20.4

[1]  $Z_S$  and  $Z_L$  defined in Figure 1.

[2] At  $P_{L(AV)} = 93$  W.

**Table 12. Typical impedance of main device at 1 : 2.5 load**

Measured load-pull data of main device;  $I_{Dq} = 810$  mA (main);  $V_{DS} = 30$  V; pulsed CW ( $t_p = 100$   $\mu$ s;  $\delta = 10$  %).

f	$Z_S$ [1]	$Z_L$ [1]	$P_{L(3dB)}$ [2]	$\eta_D$ [2]	$G_p$ [2]
(MHz)	( $\Omega$ )	( $\Omega$ )	(W)	(%)	(dB)
1440	$1.0 - j4.8$	$3.4 - j3.5$	140	65	22.0
1480	$1.4 - j5.3$	$3.3 - j3.2$	125	65	22.4
1510	$1.5 - j5.7$	$3.3 - j3.0$	120	64	23.2

[1]  $Z_S$  and  $Z_L$  defined in Figure 1.

[2] At  $P_{L(AV)} = 93$  W.

**Table 13. Typical impedance of peak device at 1 : 1 load**

Measured load-pull data of peak device;  $I_{Dq} = 1500$  mA (peak);  $V_{DS} = 30$  V; pulsed CW ( $t_p = 100$   $\mu$ s;  $\delta = 10$  %).

f	$Z_S$ [1]	$Z_L$ [1]	$P_{L(3dB)}$ [2]	$\eta_D$ [2]	$G_p$ [2]
(MHz)	( $\Omega$ )	( $\Omega$ )	(W)	(%)	(dB)
1410	$2.0 - j7.6$	$2.0 - j4.2$	380	31	19.0
1480	$3.0 - j8.0$	$1.9 - j3.6$	390	32.5	19.6
1520	$2.8 - j9.2$	$1.9 - j3.3$	380	33	20.3

[1]  $Z_S$  and  $Z_L$  defined in Figure 1.

[2] At  $P_{L(AV)} = 93$  W.

Table 14. Off-state impedances of peak device

f (MHz)	Z <sub>off</sub> (Ω)
1410	1.22 – j3.50
1480	0.57 – j1.30
1520	0.43 – j0.63

## 7.4 Test circuit

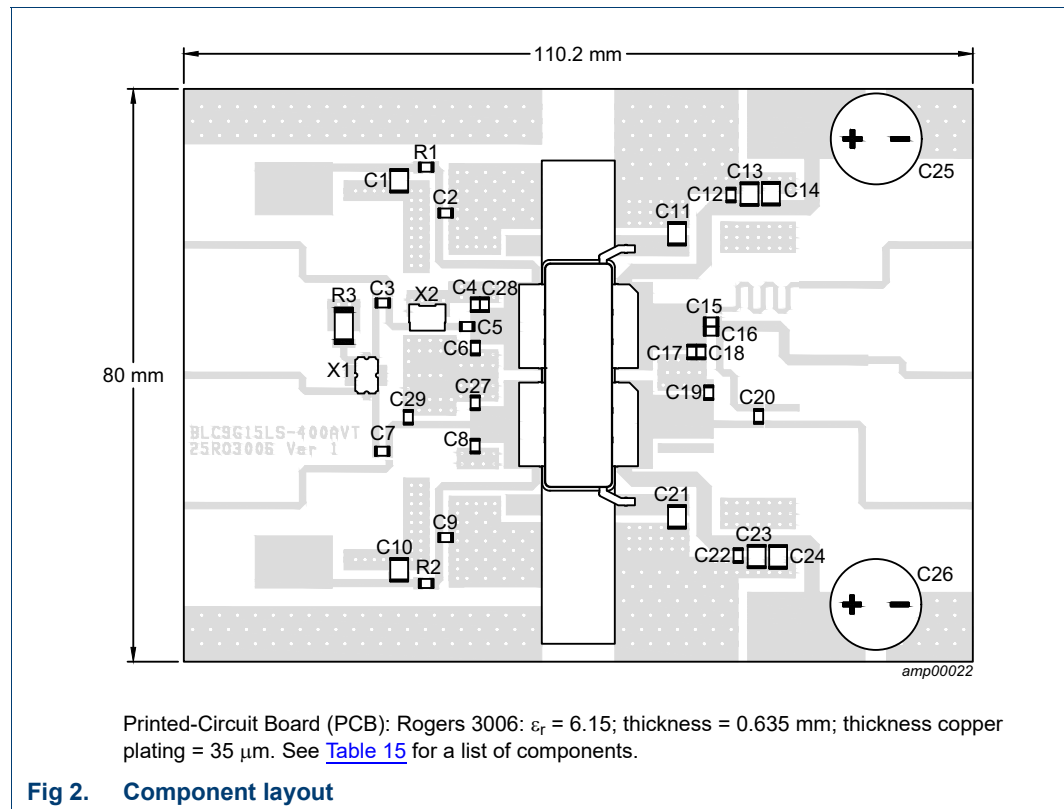


Fig 2. Component layout

Table 15. List of components

See [Figure 2](#) for component layout.

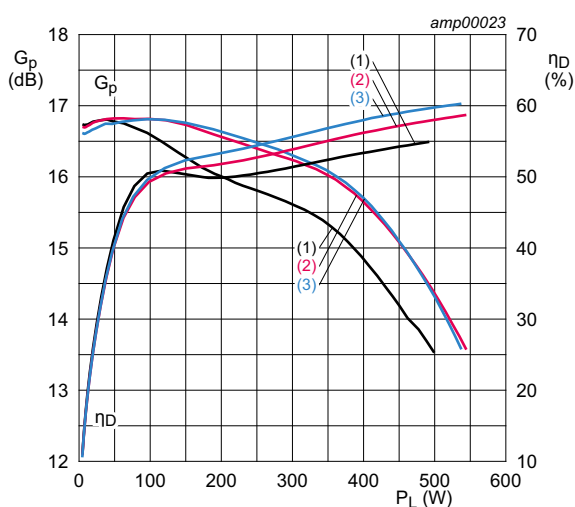
Component	Description	Value	Remarks
C1, C10, C11, C13, C14, C21, C23, C24	multilayer ceramic chip capacitor	4.7 $\mu\text{F}$	Murata GRM32ER71H475KA88L
C2, C3, C5, C7, C9, C12, C15, C16, C20, C22	multilayer ceramic chip capacitor	18 pF	Murata Hi-Q 0805
C4, C6, C27, C28	multilayer ceramic chip capacitor	2.0 pF	Murata Hi-Q 0805
C8, C17, C18	multilayer ceramic chip capacitor	1.8 pF	Murata Hi-Q 0805
C19	multilayer ceramic chip capacitor	2.7 pF	Murata Hi-Q 0805
C25, C26	electrolytic capacitor	470 $\mu\text{F}$	63 V
C29	multilayer ceramic chip capacitor	0.3 pF	ATC 100A 0805
R1, R2	SMD resistor	4.7 $\Omega$ , 1 %	0805

**Table 15. List of components ...continued**  
See [Figure 2](#) for component layout.

Component	Description	Value	Remarks
R3	SMD resistor	50 $\Omega$ , 25 W	Anaren C16A50Z4
X1	hybrid coupler	2 dB, 90°	Anaren X3C20F1-02S
X2	attenuator	1 dB	Anaren D10AAXXZ4

## 7.5 Graphical data

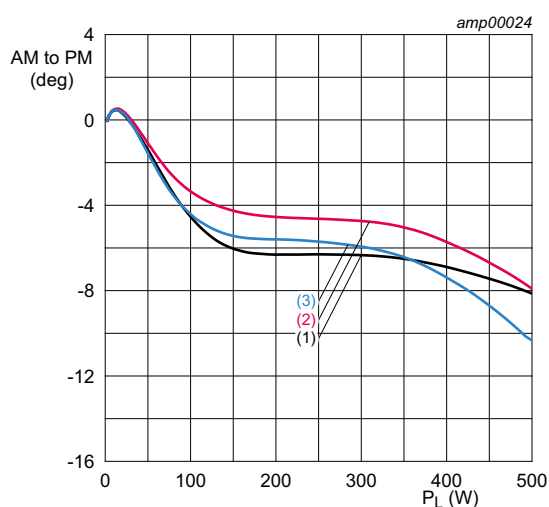
### 7.5.1 Pulsed CW



$V_{DS} = 32$  V;  $I_{Dq} = 810$  mA;  $V_{GS(amp)peak} = 0.5$  V;  
 $t_p = 100$   $\mu$ s;  $\delta = 10$  %.

- (1)  $f = 1452$  MHz
- (2)  $f = 1492$  MHz
- (3)  $f = 1511$  MHz

**Fig 3. Power gain and drain efficiency as function of output power; typical values**



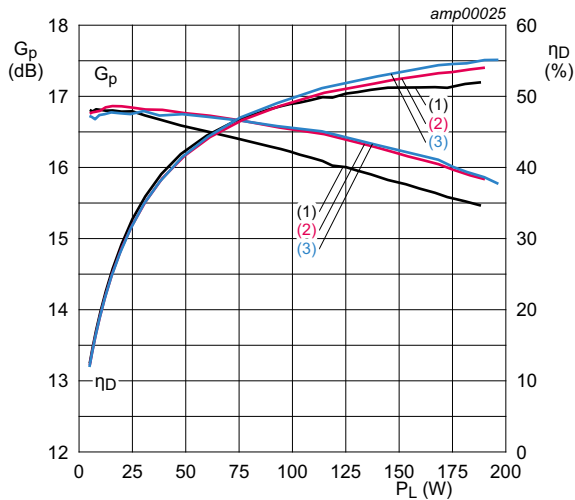
$V_{DS} = 32$  V;  $I_{Dq} = 810$  mA;  $V_{GS(amp)peak} = 0.5$  V.

- (1)  $f = 1452$  MHz
- (2)  $f = 1492$  MHz
- (3)  $f = 1511$  MHz

**Fig 4. AM to PM as a function of output power; typical values**

### 7.5.2 1-Carrier W-CDMA

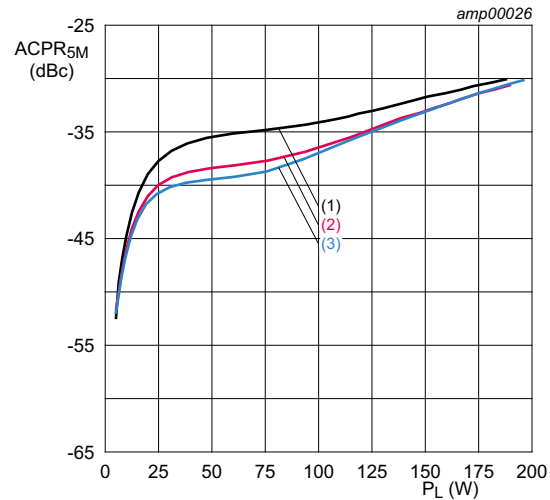
PAR = 9.6 dB per carrier at 0.01 % probability on the CCDF; 3GPP test model 1 with 64 DPCH (100 % clipping).



$V_{DS} = 32 \text{ V}$ ;  $I_{Dq} = 810 \text{ mA}$ ;  $V_{GS(amp)peak} = 0.5 \text{ V}$ .

- (1)  $f = 1454.5 \text{ MHz}$
- (2)  $f = 1489.5 \text{ MHz}$
- (3)  $f = 1508.5 \text{ MHz}$

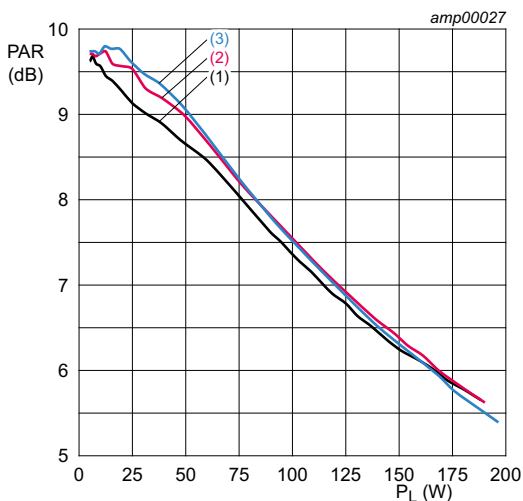
**Fig 5. Power gain and drain efficiency as function of output power; typical values**



$V_{DS} = 32 \text{ V}$ ;  $I_{Dq} = 810 \text{ mA}$ ;  $V_{GS(amp)peak} = 0.5 \text{ V}$ .

- (1)  $f = 1454.5 \text{ MHz}$
- (2)  $f = 1489.5 \text{ MHz}$
- (3)  $f = 1508.5 \text{ MHz}$

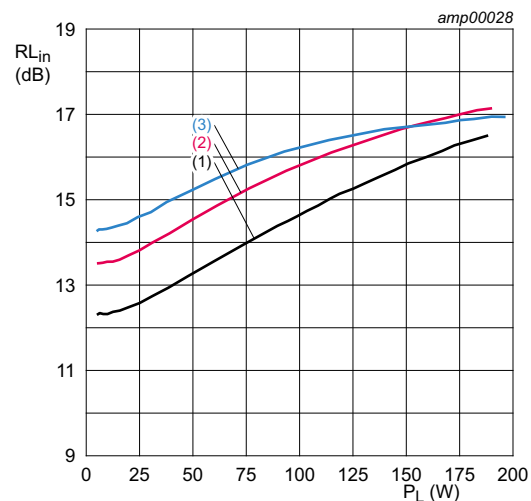
**Fig 6. Adjacent channel power ratio (5 MHz) and adjacent channel power ratio (10 MHz) as function of output power; typical values**



$V_{DS} = 32 \text{ V}$ ;  $I_{Dq} = 810 \text{ mA}$ ;  $V_{GS(amp)peak} = 0.5 \text{ V}$ .

- (1)  $f = 1454.5 \text{ MHz}$
- (2)  $f = 1489.5 \text{ MHz}$
- (3)  $f = 1508.5 \text{ MHz}$

**Fig 7. Peak-to-average power ratio as a function of output power; typical values**



$V_{DS} = 32 \text{ V}$ ;  $I_{Dq} = 810 \text{ mA}$ ;  $V_{GS(amp)peak} = 0.5 \text{ V}$ .

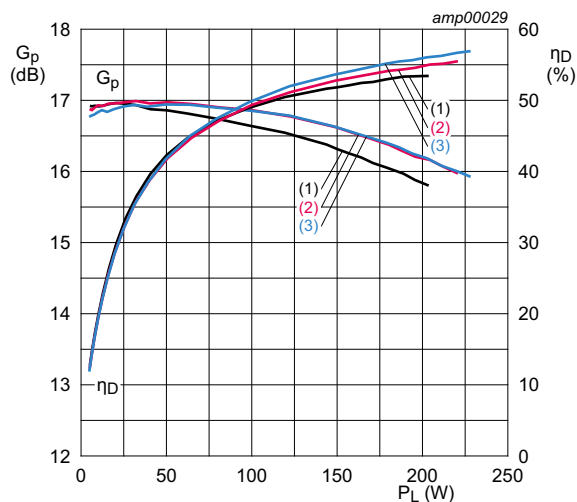
- (1)  $f = 1454.5 \text{ MHz}$
- (2)  $f = 1489.5 \text{ MHz}$
- (3)  $f = 1508.5 \text{ MHz}$

**Fig 8. Input return loss as a function of output power; typical values**



### 7.5.3 2-Carrier W-CDMA

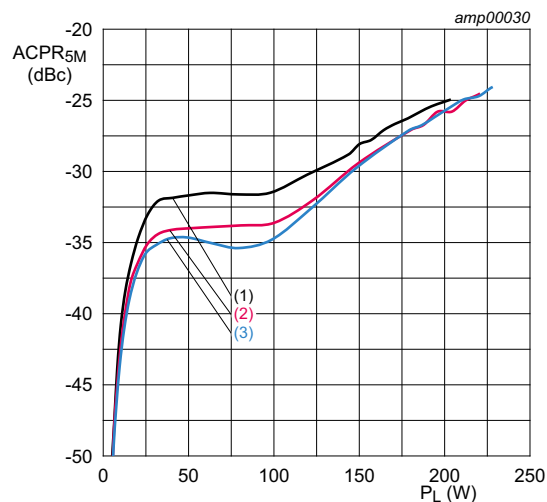
PAR = 9.6 dB at 0.01 % probability on the CCDF; 3GPP test model 1 with 64 DPCH (46 % clipping).



$V_{DS} = 32 \text{ V}$ ;  $I_{Dq} = 810 \text{ mA}$ ;  $V_{GS(amp)peak} = 0.5 \text{ V}$ .

- (1)  $f = 1457 \text{ MHz}$
- (2)  $f = 1487 \text{ MHz}$
- (3)  $f = 1506 \text{ MHz}$

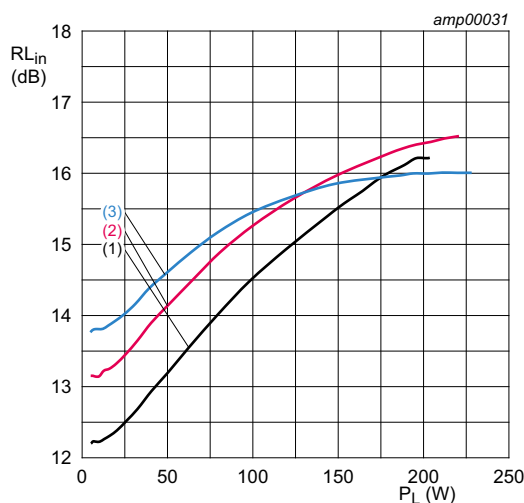
**Fig 9. Power gain and drain efficiency as function of output power; typical values**



$V_{DS} = 32 \text{ V}$ ;  $I_{Dq} = 810 \text{ mA}$ ;  $V_{GS(amp)peak} = 0.5 \text{ V}$ .

- (1)  $f = 1457 \text{ MHz}$
- (2)  $f = 1487 \text{ MHz}$
- (3)  $f = 1506 \text{ MHz}$

**Fig 10. Adjacent channel power ratio (5 MHz) and adjacent channel power ratio (10 MHz) as function of output power; typical values**

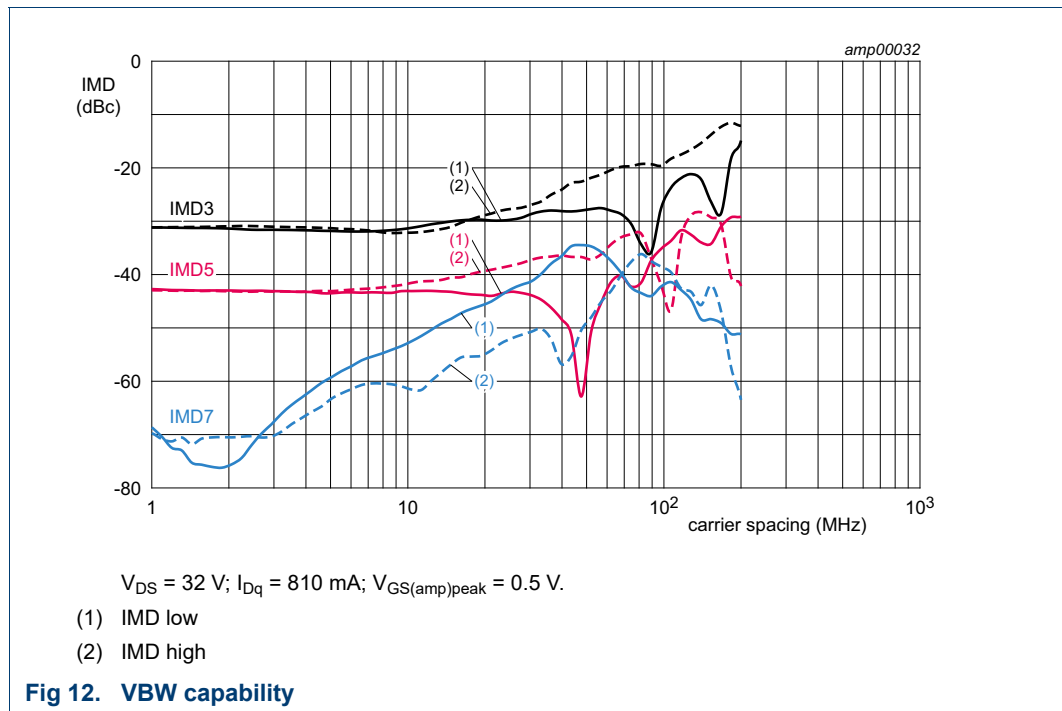


$V_{DS} = 32 \text{ V}$ ;  $I_{Dq} = 810 \text{ mA}$ ;  $V_{GS(amp)peak} = 0.5 \text{ V}$ .

- (1)  $f = 1457 \text{ MHz}$
- (2)  $f = 1487 \text{ MHz}$
- (3)  $f = 1506 \text{ MHz}$

**Fig 11. Input return loss as a function of output power; typical values**

### 7.5.4 2-Tone VBW



## 8. Package outline

Air cavity plastic earless flanged package; 6 leads

SOT1258-1

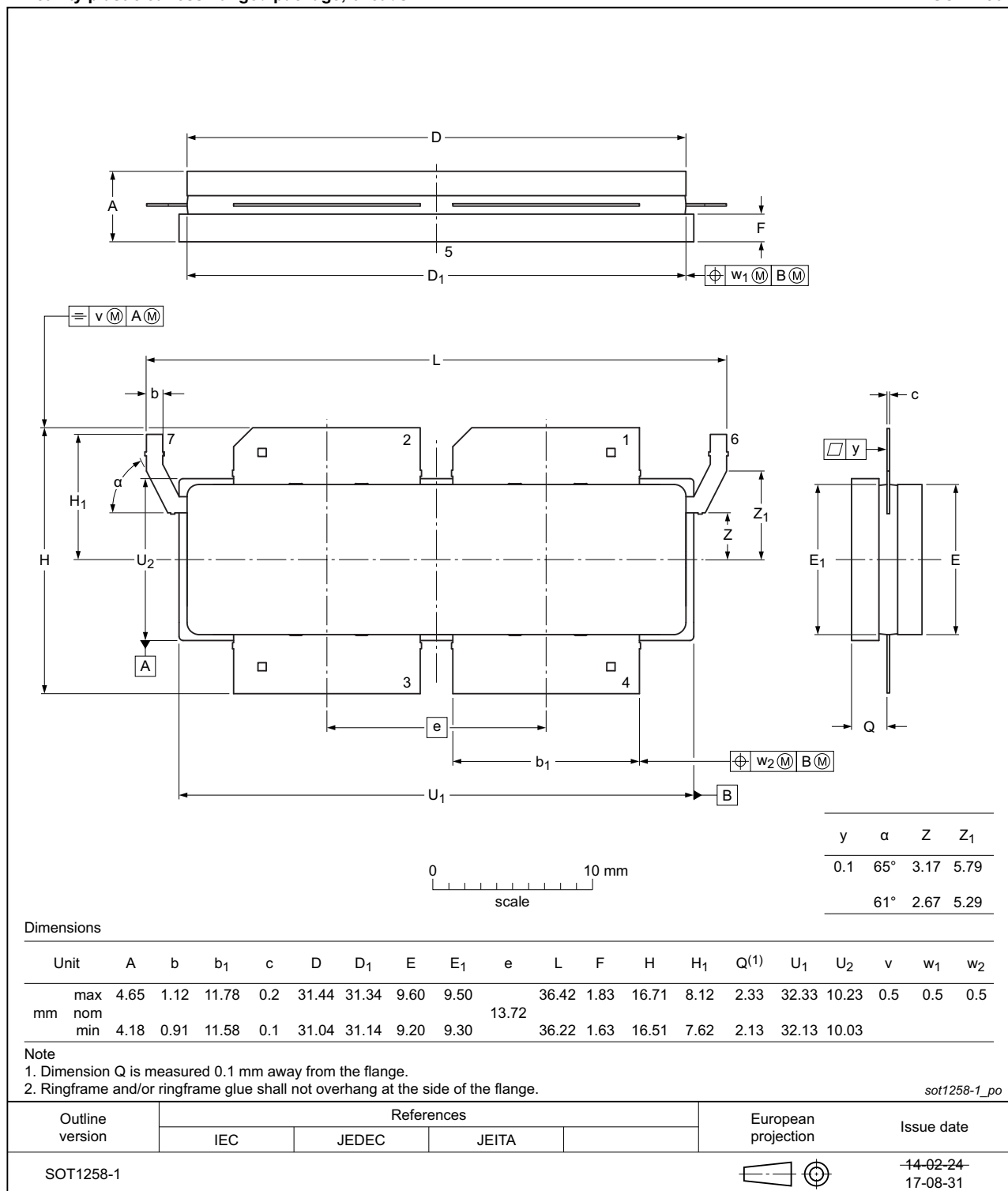


Fig 13. Package outline SOT1258-1

## 9. Handling information

### CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the *ANSI/ESD S20.20*, *IEC/ST 61340-5*, *JESD625-A* or equivalent standards.

**Table 16. ESD sensitivity**

ESD model	Class
Charged Device Model (CDM); According to ANSI/ESDA/JEDEC standard JS-002	C2A <a href="#">[1]</a>
Human Body Model (HBM); According to ANSI/ESDA/JEDEC standard JS-001	2 <a href="#">[2]</a>

[1] CDM classification C2A is granted to any part that passes after exposure to an ESD pulse of 500 V, but fails after exposure to an ESD pulse of 750 V.

[2] HBM classification 2 is granted to any part that passes after exposure to an ESD pulse of 2000 V, but fails after exposure to an ESD pulse of 4000 V.

## 10. Abbreviations

**Table 17. Abbreviations**

Acronym	Description
3GPP	3rd Generation Partnership Project
AM	Amplitude Modulation
CCDF	Complementary Cumulative Distribution Function
CW	Continuous Wave
DPCH	Dedicated Physical CHannel
ESD	ElectroStatic Discharge
LDMOS	Laterally Diffused Metal-Oxide Semiconductor
MTF	Median Time to Failure
OBO	Output Back Off
PAR	Peak-to-Average Ratio
PM	Phase Modulation
SMD	Surface Mounted Device
VBW	Video Bandwidth
VSWR	Voltage Standing Wave Ratio
W-CDMA	Wideband Code Division Multiple Access

## 11. Revision history

Table 18. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BLC9G15LS-400AVT v.3	20171124	Product data sheet	-	BLC9G15LS-400AVT v.2
Modifications:	<ul style="list-style-type: none"> <li>• <a href="#">Table 2 on page 2</a>: changed simplified version drawing SOT1258-3 to SOT1258-1</li> <li>• <a href="#">Table 3 on page 2</a>: changed version SOT1258-3 to SOT1258-1</li> <li>• <a href="#">Figure 13 on page 11</a>: changed package outline drawing SOT1258-3 to SOT1258-1</li> </ul>			
BLC9G15LS-400AVT v.2	20161202	Product data sheet	-	BLC9G15LS-400AVT v.1
BLC9G15LS-400AVT v.1	20160317	Product data sheet	-	-

## 12. Legal information

### 12.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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